



NOTES:

- 1) STANDARD NI/PD/AU PLATING STACK UP
 40 micorinches Ni minimum
 .8 microinches Pd minimum
 .2 microinches Au minimum
- 2) DELIVERY IN TUBES
- 3) * MARKS CRITICAL DIMENSION
- 4) PART MEETS RoHS COMPLIANCE

REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	01/05	
B	ADD "IO" AND "GROUND" TO DIE PADS	10/07	

UNLESS OTHERWISE SPECIFIED:	NAME	DATE
DIMENSIONS ARE IN MM TOLERANCES:	DRAWN	JGORDON 1/25/05
TWO PLACE DECIMAL ±.10 if not otherwise specified	CHECKED	
THREE PLACE DECIMAL ±.05	ENG APPR.	
INTERPRET GEOMETRIC TOLERANCING PER:	MFG APPR.	
MATERIAL	Q.A.	
NI/PD/AU PLATING	COMMENTS:	
FINISH		
finish		
DO NOT SCALE DRAWING		

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TITLE: 6X6mm SFN PACKAGE		
SIZE A	DWG. NO. 56-00SFN-000	REV B
SCALE: 1:0.1		SHEET 1 OF 1